For IEC use only	47/2869/DA 2024-08-23

INTERNATIONAL ELECTROTECHNICAL COMMISSION

TECHNICAL COMMITTEE No. 47: SEMICONDUCTOR DEVICES

Draft agenda for the TC 47 plenary meeting to be held in London, United Kingdom on November 29th 2024 (starting time: 9:00 am to approximate finishing time: 12:30 pm)

Item	Description	Documents
1	Opening of the meeting and IEC code of conduct	
2	Approval of the agenda	47/2869/DA
3	Review of the last meeting minutes held on 2022-11-17	47/2839/RM
4	Information from IEC Secretariat	
5	Report of the Secretary	
6	Reports of Working Groups in TC 47	
	WG 1: Terminology	
	- Report of the WG 1 activity in general	
	WG 2: Semiconductor device test methods and guidelines - Mechanical, climatic and storage	
	- Report of the WG 2 activity in general	
	WG 5: Wafer level reliability for semiconductor devices	
	- Report of the WG 5 activity in general	
	WG 6: Incubating Working Group	
	- Report of the WG 6 activity in general	
	WG 7: Semiconductor devices for energy conversion and transfer	
	- Report of the WG 7 activity in general	
	WG 8: Wide bandgap technologies – Power electronic conversion	
	- Report of the WG 8 activity in general	
	PT 63492: Isolation for semiconductor devices	
	- Report of the PT 63492 activity in general	
7	Review and update the Work Programme and the project plans of TC 47 as displayed on the IEC website	
8	Review of stability dates	
9	Review of P-members participation	47/XXXX/INF
10	Reports of Subcommittees in TC 47 • SC 47A: Integrated circuits	

Item	Description	Documents
	• SC 47D: Semiconductor devices packaging • SC 47E: Discrete semiconductor devices • SC 47F: Micro-electromechanical systems	

11	Review liaisons
	- Internal IEC Liaison
	  • TC 56: Dependability (Liaison representative: Mr. Nicholas E.F. Lycoudes)
	  • TC 91: Electronics assembly technology (Liaison representative: Mr. Jim Lynch)
	  • TC 101: Electrostatics (Liaison representative: Mr. Jim Lynch)
	  • TC 107: Process management for avionics (Liaison representative: Mr. Nick Lycoudes)
	  • TC 110: Electronic displays (Liaison representative: Mr. Sung Hoon Choa)
	  • TC 111: Environmental standardization for electrical and electronic products and systems (Liaison representative: Mr. Stephen Tisdale)
	  • TC 113: Nanotechnology for electrotechnical products and systems (Liaison representative: Mr. Joonho Bae)
	  • TC 119: Printed Electronics (Liaison representative: Mr. Hojun Ryu)
	  • TC 124: Wearable electronic devices and technologies (Liaison representative: Mr. Deok-kee Kim)
	- Liaison with ISO
	  • ISO TC 22/SC 31: Data communication (Liaison representative: Mr. Werner Berns)
	- Liaison C
	  • EIA: WG 1, WG 2, WG 3 and WG 5 (Liaison representative: Mr. Nicholas E.F. Lycoudes)	

12	Review the Strategic Business Plan (SBP)	SMB/8116/R
13	Any other business - New WG on isolation technologies - New WG on neuromorphic devices - Expert nomination to ACEA - Update from German NC on Trusted Chips Kick-off	
14	Date and place of the next meeting - GM 2025 will be held in India	
15	Review of decisions	
16	Close of the meeting	

Please note that an electronic version of this Draft Agenda in which hyperlinks have been established will be available on the IEC website four weeks prior to the meeting.